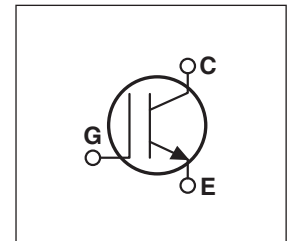


Thunderbolt IGBT®

The Thunderbolt IGBT® is a new generation of high voltage power IGBTs. Using Non-Punch Through Technology, the Thunderbolt IGBT® offers superior ruggedness and ultrafast switching speed.

- Low Forward Voltage Drop
- High Freq. Switching to 80KHz
- Low Tail Current
- Ultra Low Leakage Current
- RBSOA and SCSOA Rated



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT100GT60JR	UNIT
V_{CES}	Collector-Emitter Voltage	600	Volts
V_{GE}	Gate-Emitter Voltage	± 30	
I_{C1}	Continuous Collector Current @ $T_C = 25^\circ\text{C}$	148	Amps
I_{C2}	Continuous Collector Current @ $T_C = 100^\circ\text{C}$	80	
I_{CM}	Pulsed Collector Current ^①	300	
SSOA	Switching Safe Operating Area @ $T_J = 150^\circ\text{C}$	300A @ 600V	
P_D	Total Power Dissipation	500	Watts
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage ($V_{GE} = 0\text{V}, I_C = 4\text{mA}$)	600			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ($V_{CE} = V_{GE}, I_C = 1.5\text{mA}, T_J = 25^\circ\text{C}$)	3	4	5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ($V_{GE} = 15\text{V}, I_C = 100\text{A}, T_J = 25^\circ\text{C}$)	1.7	2.1	2.5	
	Collector-Emitter On Voltage ($V_{GE} = 15\text{V}, I_C = 100\text{A}, T_J = 125^\circ\text{C}$)		2.5		
I_{CES}	Collector Cut-off Current ($V_{CE} = 600\text{V}, V_{GE} = 0\text{V}, T_J = 25^\circ\text{C}$) ^②			25	μA
	Collector Cut-off Current ($V_{CE} = 600\text{V}, V_{GE} = 0\text{V}, T_J = 125^\circ\text{C}$) ^②			TBD	
I_{GES}	Gate-Emitter Leakage Current ($V_{GE} = \pm 30\text{V}$)			300	nA

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT100GT60JR

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT	
C_{ies}	Input Capacitance	Capacitance $V_{GE} = 0V, V_{CE} = 25V$ $f = 1 \text{ MHz}$		5150		pF	
C_{oes}	Output Capacitance			475			
C_{res}	Reverse Transfer Capacitance			295			
V_{GEP}	Gate-to-Emitter Plateau Voltage	Gate Charge $V_{GE} = 15V$ $V_{CE} = 300V$ $I_C = 100A$		8.0		V	
Q_g	Total Gate Charge ^③			460			
Q_{ge}	Gate-Emitter Charge			40			
Q_{gc}	Gate-Collector ("Miller") Charge			210			
SSOA	Switching Safe Operating Area	$T_J = 150^\circ\text{C}, R_G = 4.3\Omega, V_{GE} = 15V, L = 100\mu\text{H}, V_{CE} = 600V$	300			A	
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 100A$ $R_G = 4.3\Omega$ $T_J = +25^\circ\text{C}$		40		ns	
t_r	Current Rise Time			75			
$t_{d(off)}$	Turn-off Delay Time			320			
t_f	Current Fall Time			100			
E_{on1}	Turn-on Switching Energy ^④				3250		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤				3525		
E_{off}	Turn-off Switching Energy ^⑥				3125		
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 100A$ $R_G = 4.3\Omega$ $T_J = +125^\circ\text{C}$		40		ns	
t_r	Current Rise Time			75			
$t_{d(off)}$	Turn-off Delay Time			350			
t_f	Current Fall Time			100			
E_{on1}	Turn-on Switching Energy ^④				3275		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤				4650		
E_{off}	Turn-off Switching Energy ^⑥				3750		

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case (IGBT)			.25	°C/W
$R_{\theta JC}$	Junction to Case (DIODE)			N/A	
W_T	Package Weight		29.2		gm
$V_{Isolation}$	RMS Voltage (50-60Hz Sinusoidal Waveform From Terminals to Mounting Base for 1 Min.)	2500			Volts

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② For Combi devices, I_{ces} includes both IGBT and FRED leakages
- ③ See MIL-STD-750 Method 3471.
- ④ E_{on1} is the clamped inductive turn-on energy of the IGBT only, without the effect of a commutating diode reverse recovery current adding to the IGBT turn-on loss. Tested in inductive switching test circuit shown in figure 21, but with a Silicon Carbide diode.
- ⑤ E_{on2} is the clamped inductive turn-on energy that includes a commutating diode reverse recovery current in the IGBT turn-on switching loss. (See Figures 21, 22.)
- ⑥ E_{off} is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1. (See Figures 21, 23.)

APT Reserves the right to change, without notice, the specifications and information contained herein.

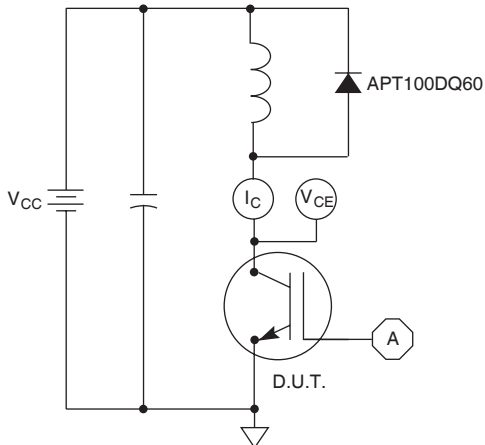


Figure 21, Inductive Switching Test Circuit

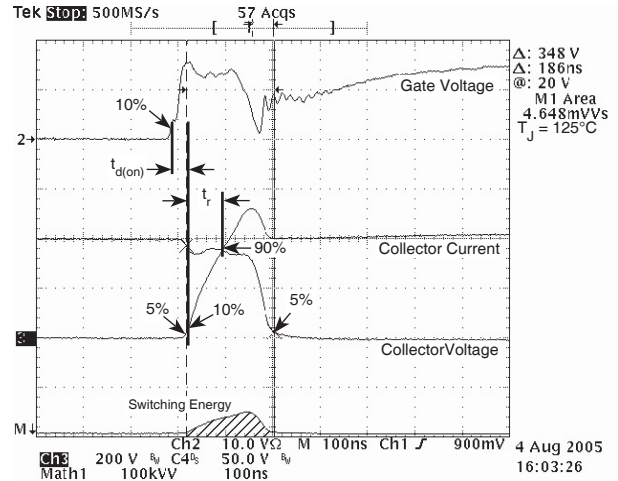


Figure 22, Turn-on Switching Waveforms and Definitions

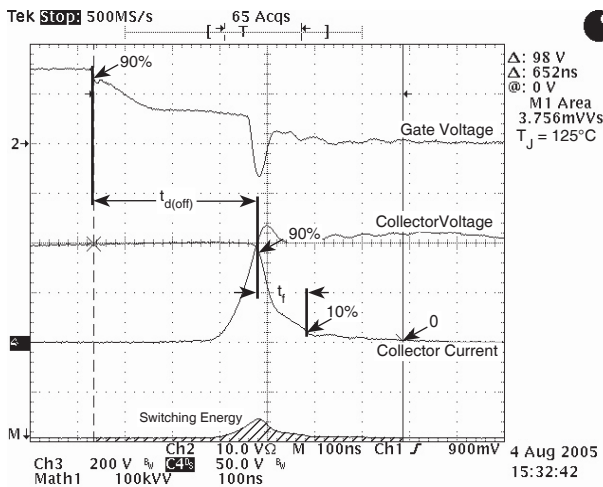
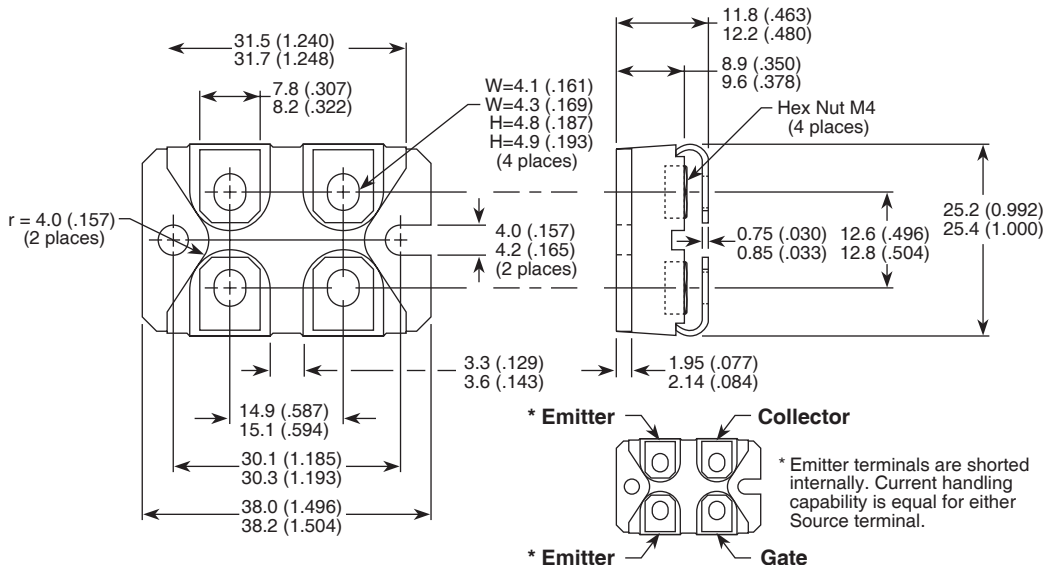


Figure 23, Turn-off Switching Waveforms and Definitions

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)

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